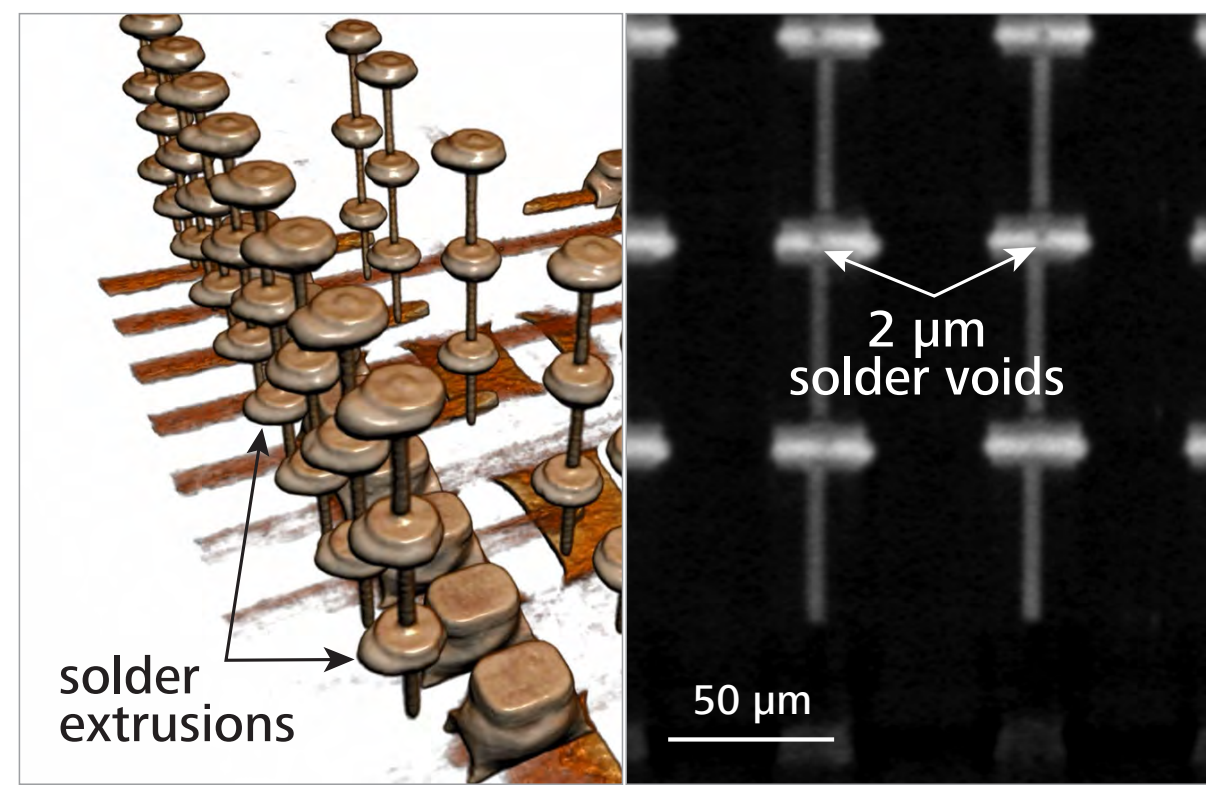


ZEISS Xradia Versa 3D X-ray Microscopes

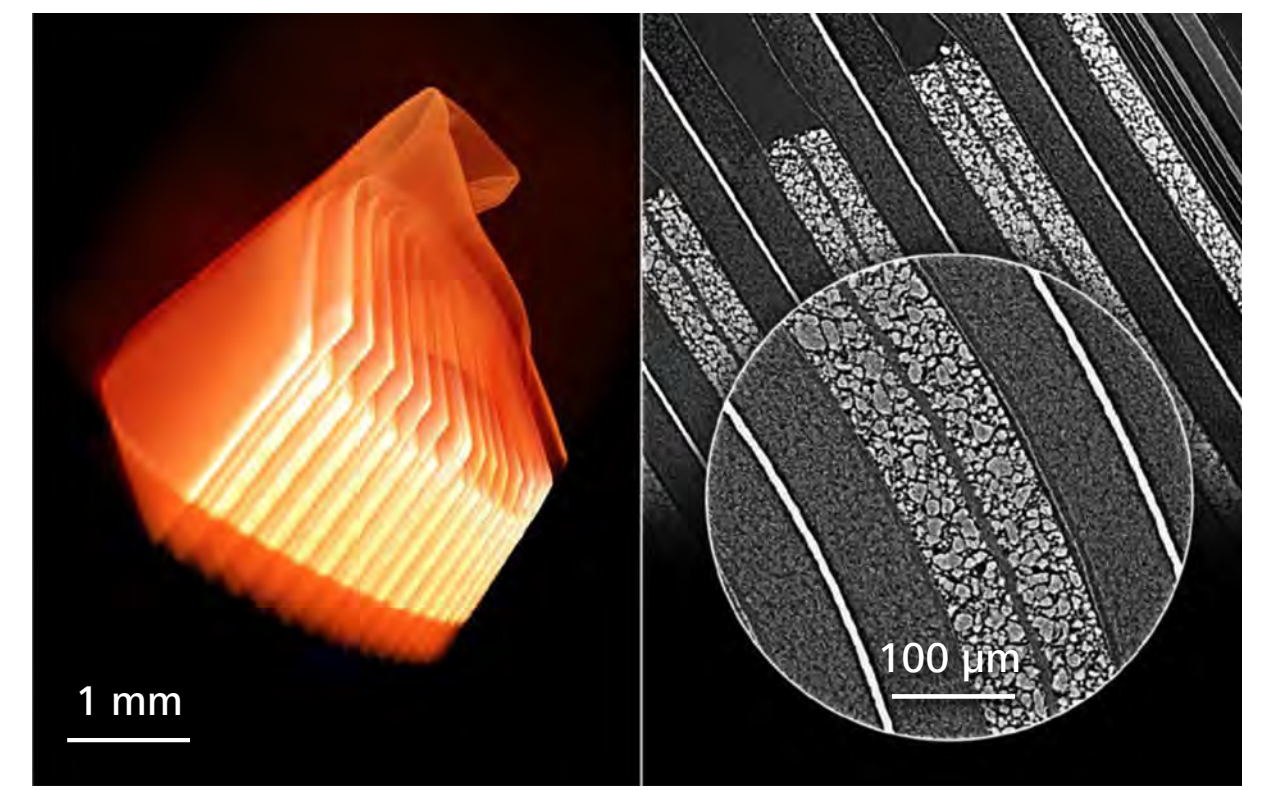
Seeing beyond

Improving failure analysis success rates of advanced electronic packages



3D XRM Image Virtual Cross Section

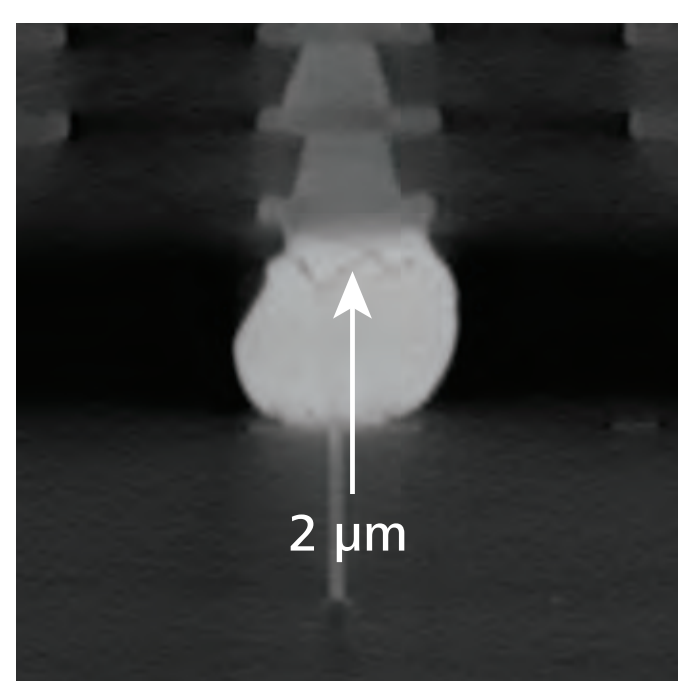
*DRAM stacked die interconnect in
10 mm x 7 mm x 1 mm package, 0.8 μm/voxel.*



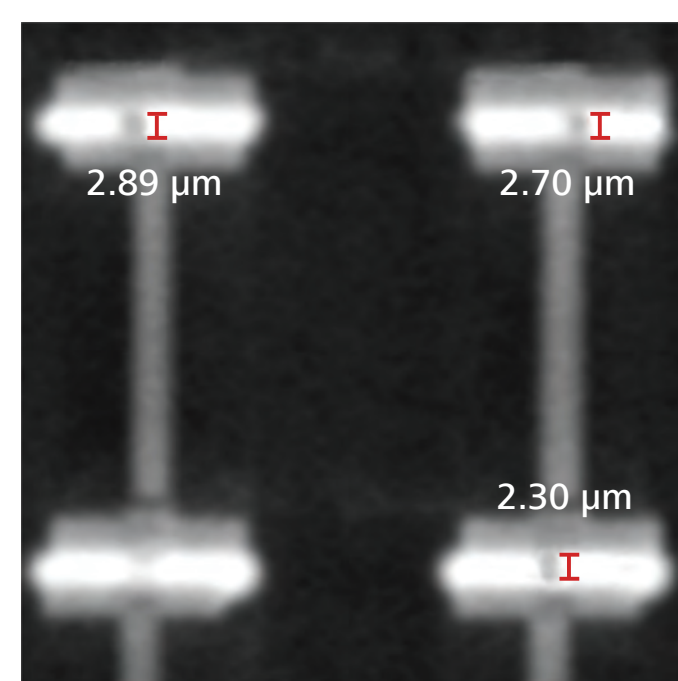
3D XRM Image Virtual Cross Section

*Images from intact lithium ion battery,
0.53 and 0.25 μm/voxel respectively.*

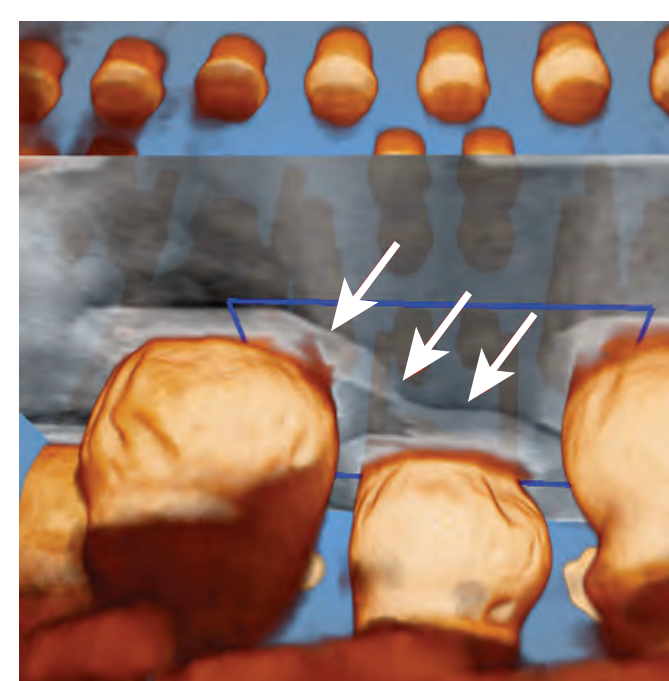
High resolution and high contrast imaging for intact packages



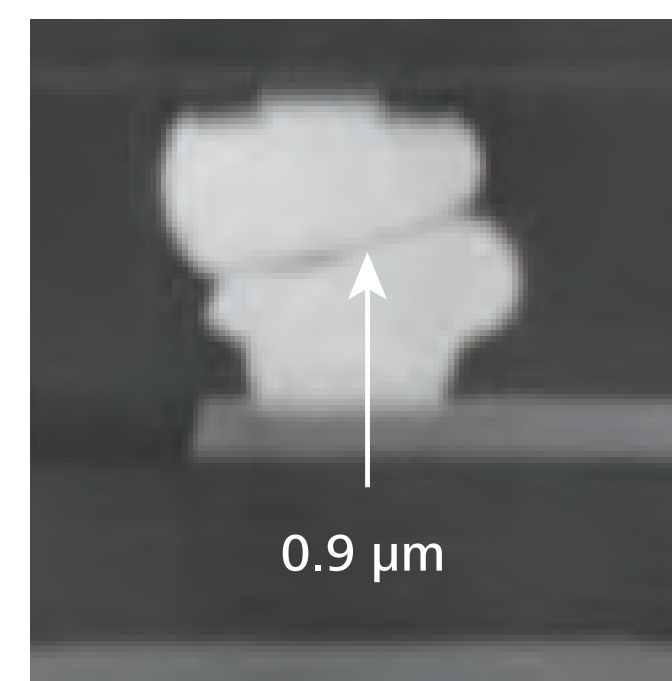
C4 Cracks



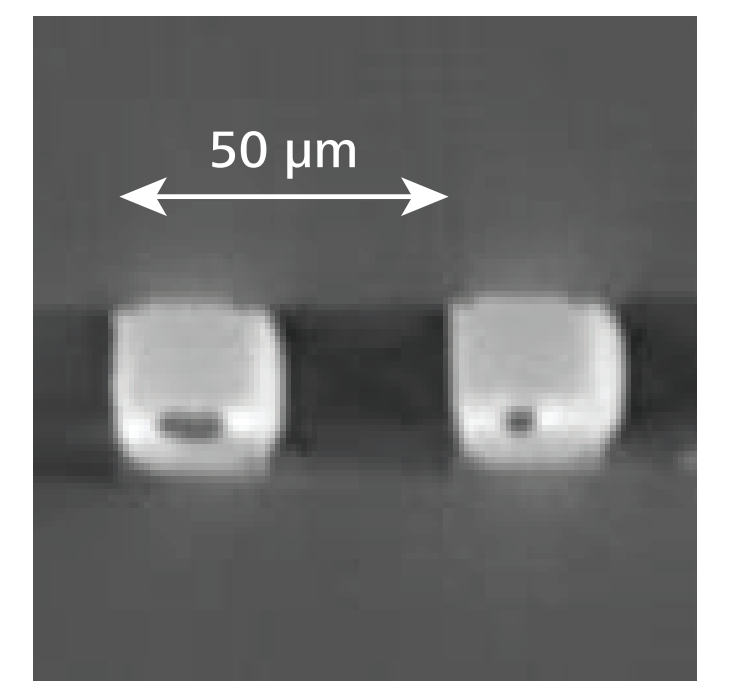
Microbump Voids



Solder Bleed



Head in Pillow



Voids

